



Final Product/Process Change Notification

Document #:FPCN25729ZE

Issue Date:21 Feb 2025

Title of Change:	Wafer Fab Site Addition of onsemi, Bucheon Korea as Alternate Fab Site for ESD and Surge Protection Products and Datasheet Update	
Proposed Changed Material First Ship Date:	28 Aug 2025 or earlier if approved by customer	
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>	
Product Category:	Active components – Discrete components	
Contact information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	31 Jan 2025	
PPAP Availability Date:	28 Feb 2025	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor	
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	
Data Sheet	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification	
Description and Purpose:		
This notification is to advise customers of the dual source wafer fab strategy for the devices listed in the Affected Parts List. Upon implementation of this FPCN, parts can be sourced from either LA Semiconductor or onsemi Bucheon, Korea.		
	From	To
Manufacturing location for Wafer Fab	LA Semiconductor, Idaho, United States	LA Semiconductor, Idaho, United States onsemi Bucheon, Korea
The clamping voltage of 8/20 μ s waveform for all products listed in this FPCN will be revised as below. The datasheet will reflect the changes upon full customer approval.		

Test Item	Conditions	Current Max	New Max
Clamping Voltage (VC) (pulse width = 8/20 us)	IPP = 1 A, Any I/O to GND	8.5 V	9.0 V
	IPP = 5 A, Any I/O to GND	9.0 V	10.5 V
	IPP = 8 A, Any I/O to GND	10.0 V	11.5 V
	IPP = 25 A, Any I/O to GND	12.0 V	14.0 V

There are no product marking changes as a result of this change.

Reason / Motivation for Change:	Source/Supply/Capacity Changes
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	<p>The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded.</p> <p>No anticipated impacts.</p>

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Bucheon, Korea	None

Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code
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Reliability Data Summary:

QV DEVICE NAME: SZNSP4201MR6T1G

RMS: 97122

PACKAGE: TSOP6

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/ 231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/ 231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @260°C		0/693
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/ 231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/ 231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/ 231

NOTE: AEC-1pager is attached.

To view attachments:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file

Electrical Characteristics Summary:

Limits have been changed per described in the details section for the part numbers listed in Affected Parts.



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
SZTVS4201MR6T1G	#NONE	SZNSP4201MR6T1G
SZNSP2201MR6T1G	#NONE	SZNSP4201MR6T1G
SZNSP4201MR6T1G	#NONE	SZNSP4201MR6T1G